FIG. (A) FORMATION OF INSULATING LAYER 10/a

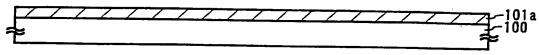


FIG. 1(B) SEQUENTIAL FORMATION OF INSULATING LAYER 1016 AND

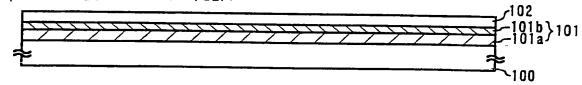


FIG. 1(C) CRYSTALL IZATION

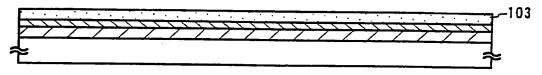


FIG. 1(D) FORMATION OF ACTIVE LAYER AND GATE INSULATING FILM

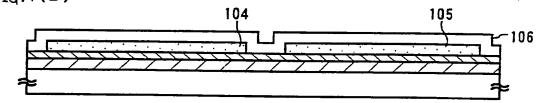
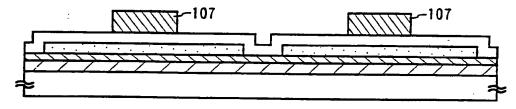


FIG. (E) FORMATION OF GATE WIRING



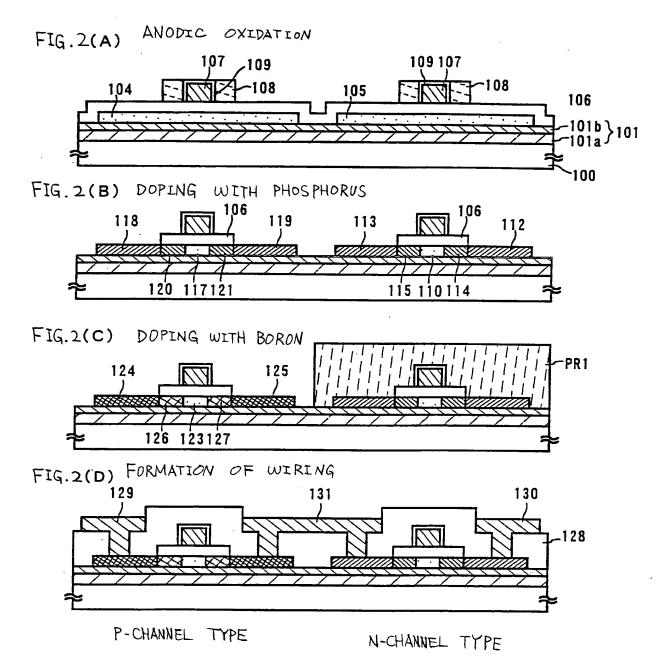
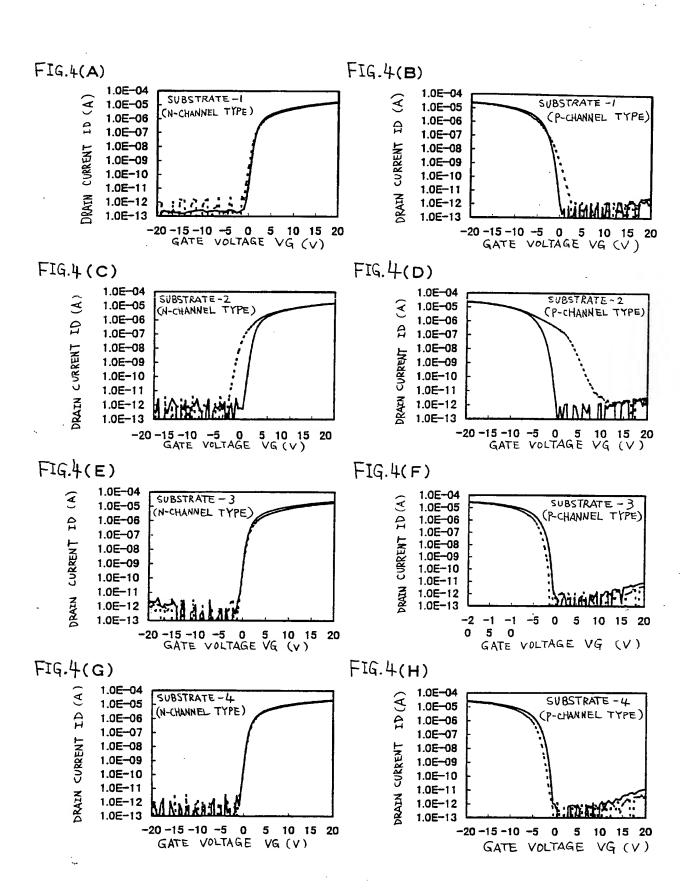


FIG.3

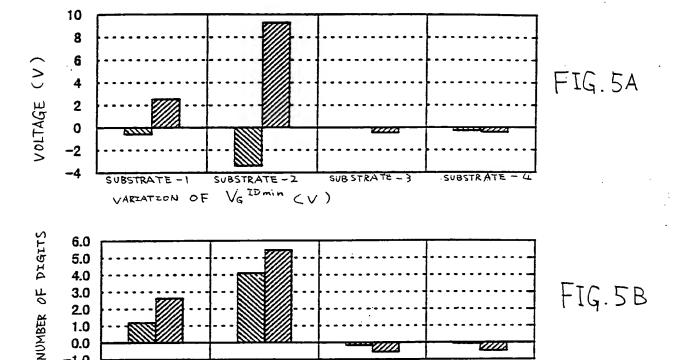
		SUBSTRATE - 1	SUBSTRATE	-2 SUBSTRATE - 3	SUBSTRATE-4
FLOW RATE OF RAW MATERIAL GAS	SiH4	4	4		15
	N₂O	400		20	20
	NH3			100	200
HEAT TREATMENT		CONDUCTED	NO	NO	NO
COMPOSITION RATIO (atomic %)	7	7. 0)	24. 0	44. 1
	0	59.	5	26. 5	6. 0
	Si	32.	0	33. 0	34. 4
	Н	1. 5		16. 5	15. 5
REFRACTIVE INDEX		1. 45	66	1. 7468	1. 7975

FILM FORMING CONDITIONS AND PHYSICAL PROPERTIES OF INSULATING LAYER (SILICON OXIDE NITRIDE LAYER) 10/9



1.0 0.0 -1.0 & N-CHANNEL TYPE (L/W = 5.6/7.5 Mm) (L/w = 5.6/7.5 mm) P-CHANNEL TYPE

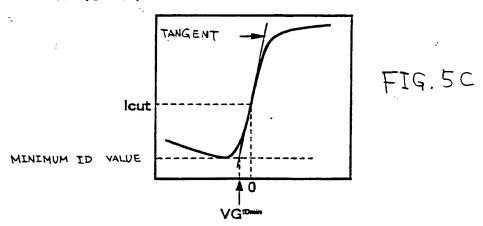
SUBSTRATE-4



CHANGE OF NUMBER OF DIGITS OF I cut

X STRESS CONDITIONS 150°C, I hour, VG: 20V (N-CHANNEL TYPE), -ZOV (P-CHANNEL TYPE), VD=VS= 0 V

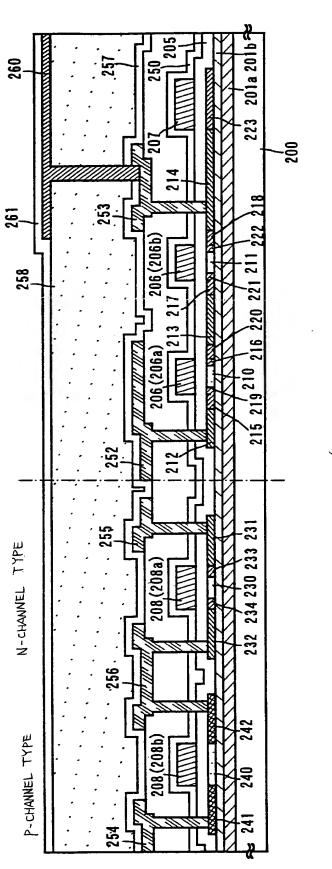
SUBSTRATE-3



ID-VG CHARACTERISTIC CURVE

PIXEL MATRIX CIRCUIT

DRIVER CIRCUIT (CMOS CIRCUIT)



FORMATION OF UNDERLYING FILM, ACTIVE LAYER AND GATE INSULATING FILM

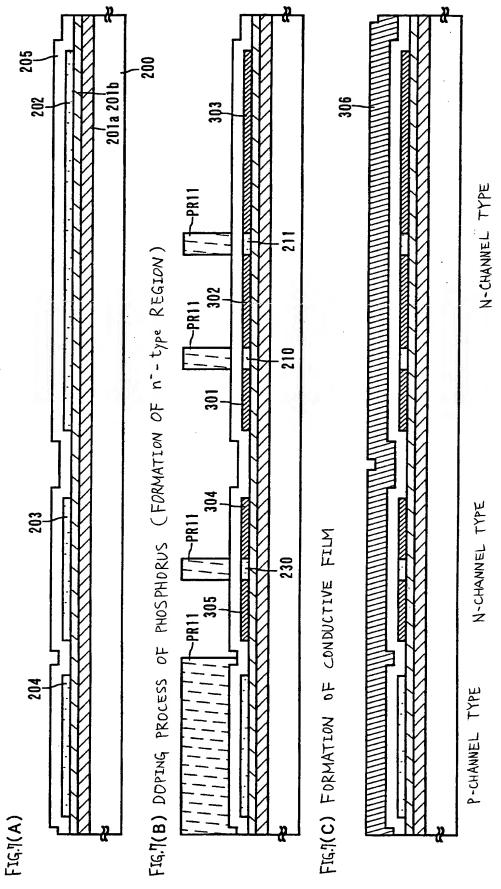


FIG.8(A) DOPING WITH BORON (FORMATION OF P'-TYPE REGION)

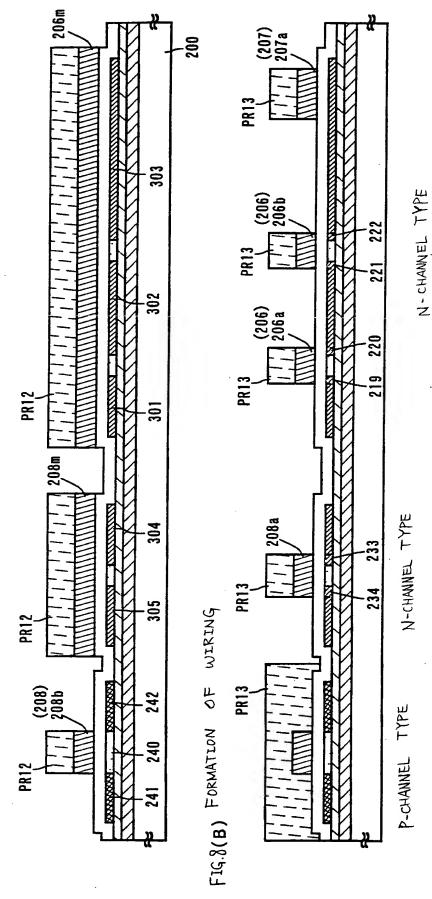
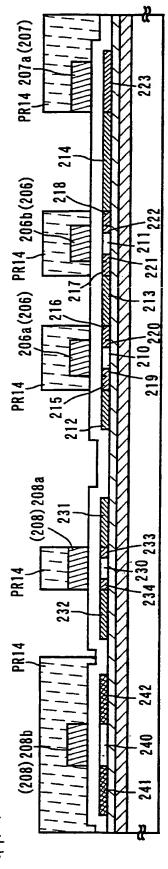
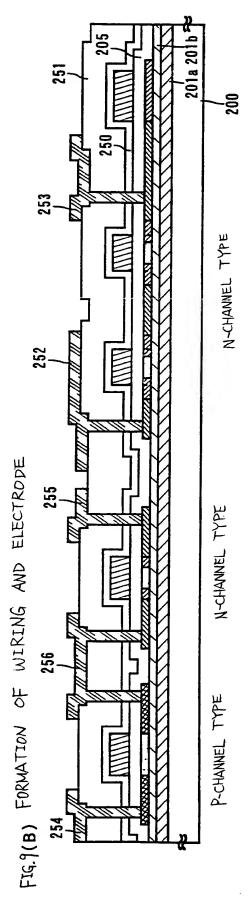
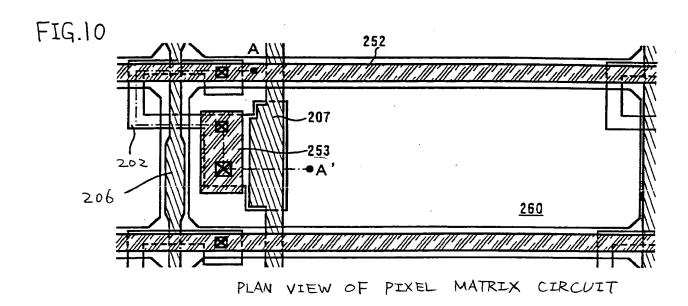
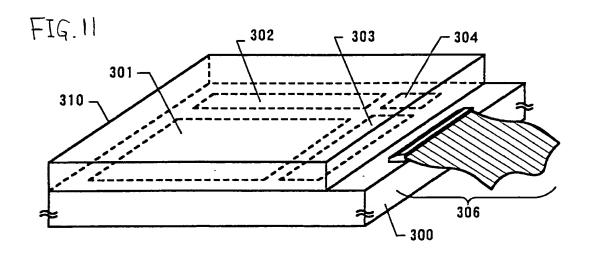


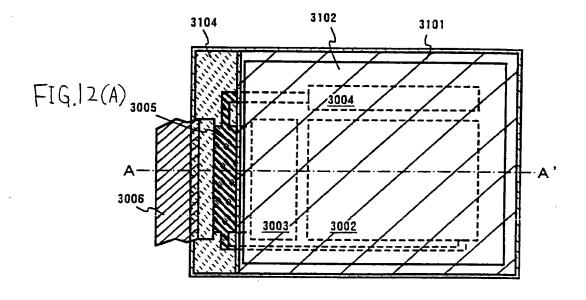
FIG. 9(A) DOPING WITH PHOSPHORUS (FORMATION OF N+-TYPE REGION)

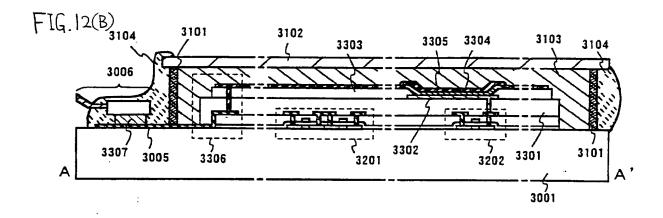


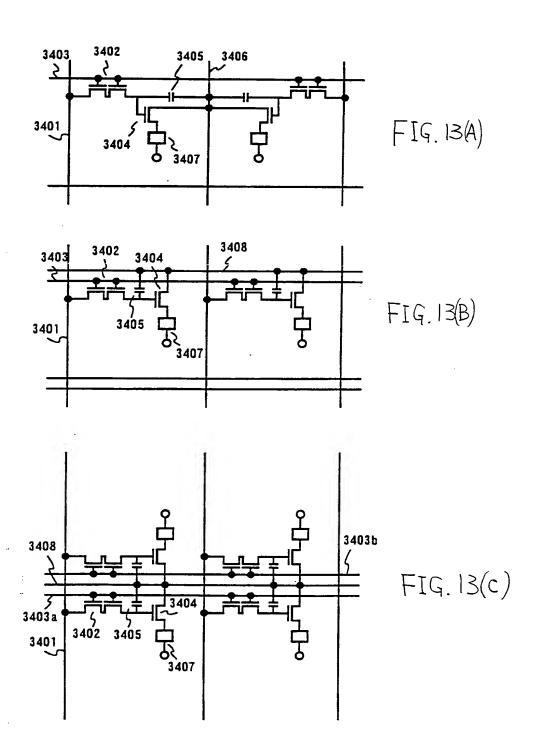


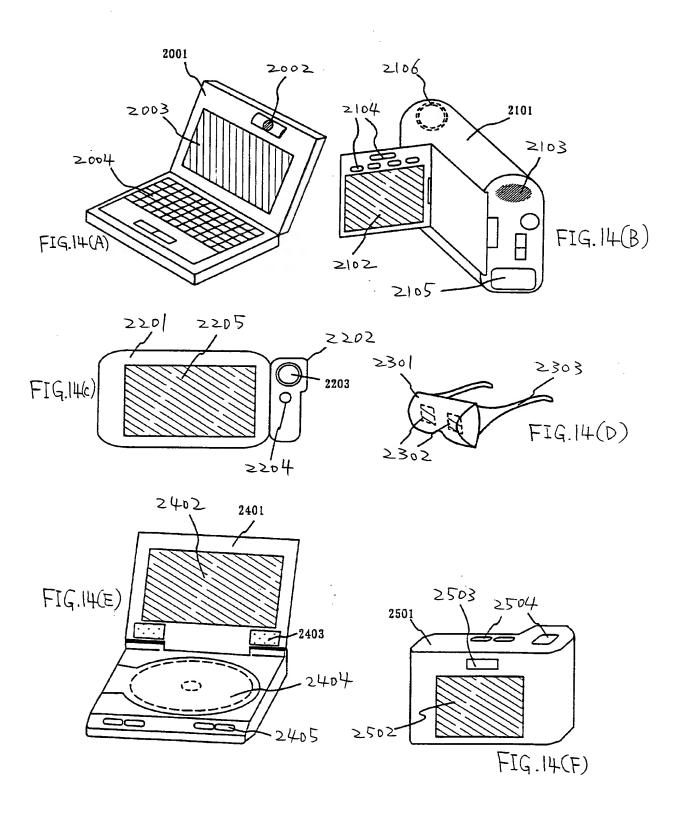


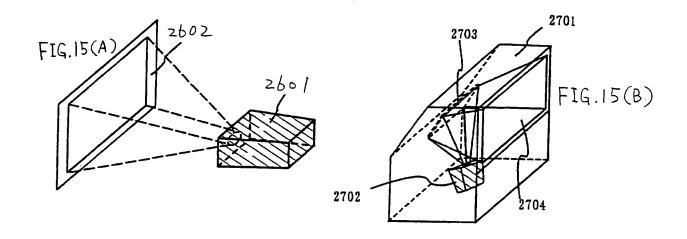












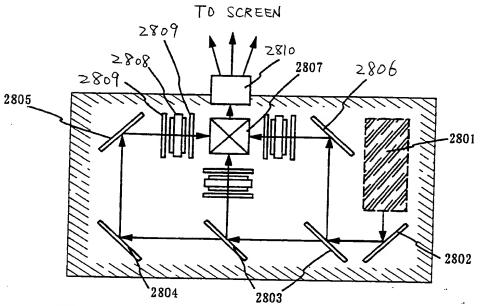
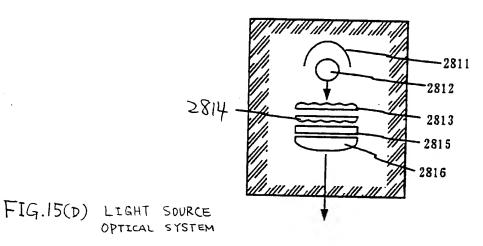
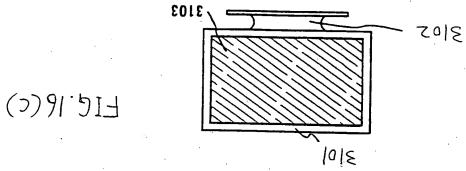


FIG. 15(c) PROJECTION UNIT (THREE-LENS TYPE)





300E 300E 300E

50bz 10bz 70bz 70bz

FIG.16(A)